

Marked UP Claims

9. The manufacturing process for a printed wiring board according to any of claims 5 to 8, characterized in that said organic layer is formed with one or two selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids.

10. The manufacturing process for a printed wiring board according to any of claims 5 to 8, characterized in that said organic layer is formed by repeatedly applying an organic agent constituted of one or constituted as a mixture of two or more selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids several times.

15. The manufacturing process for a printed wiring board according to any of claims 5 to 8, characterized in that said organic layer is formed by alternately applying two organic agents or more selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids several time.

20. The manufacturing process for a printed wiring board according to any of claims 5 to 8, characterized in that said organic layer is formed by alternately applying two organic agents or more selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids several time.

25. The manufacturing process for a printed wiring board according to any of claims 5 to 8, characterized in that said organic layer is formed by alternately applying two organic agents or more selected from the group consisting of nitrogen-containing organic compounds, sulfur-containing organic compounds and carboxylic acids several time.